

TH 979

Silicone Thermal Pad

Description

TH 979 is a thermally conductive silicone interface pad designed to provide a better heat-transfer path between the heat-generating IC package and heat sink or other cooling devices. It is designed for superior thermal conduction and high electrical insulation. This silicone pad comes with both sides non-tacky and can be cut into the shapes required.

Applications

1. Thermal conductive interface material for electronic parts and devices.

Guidelines for Use

1. Wear rubber gloves when handling the silicone pad.
2. Pick up the silicone thermal pad from the container using hand.
3. Place the silicone thermal pad onto the required electronic part and circuit.
4. No heating nor curing is required.
5. The thermal pad can be applied and removed easily. Care must be taken during installation to avoid tearing.

Properties

Property	Test Method	Unit	Typical Value
Chemical type	-	-	Silicone
Appearance	Pen 10	-	White
Surface tack	-	-	Non tacky
Thermal conductivity	ISO/DIS 22007	W/mK	1.8
Volatile content	PEN 92	%	< 1.0
Tensile Strength	PEN 41	kg/cm ²	5.0-7.0
Elongation	PEN 41	%	8.0-13.0
Hardness	Pen 29	Shore A	50
Specific gravity (cured)	Pen 14	-	2.2

Storage

Store this silicone thermal pad in an air tight container in a cool (20°C to 30°C) and dark place to prolong shelf life. Keep away from moisture.

Packaging & Dimension

- Sheet form
- Will provide customized dimension if required

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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